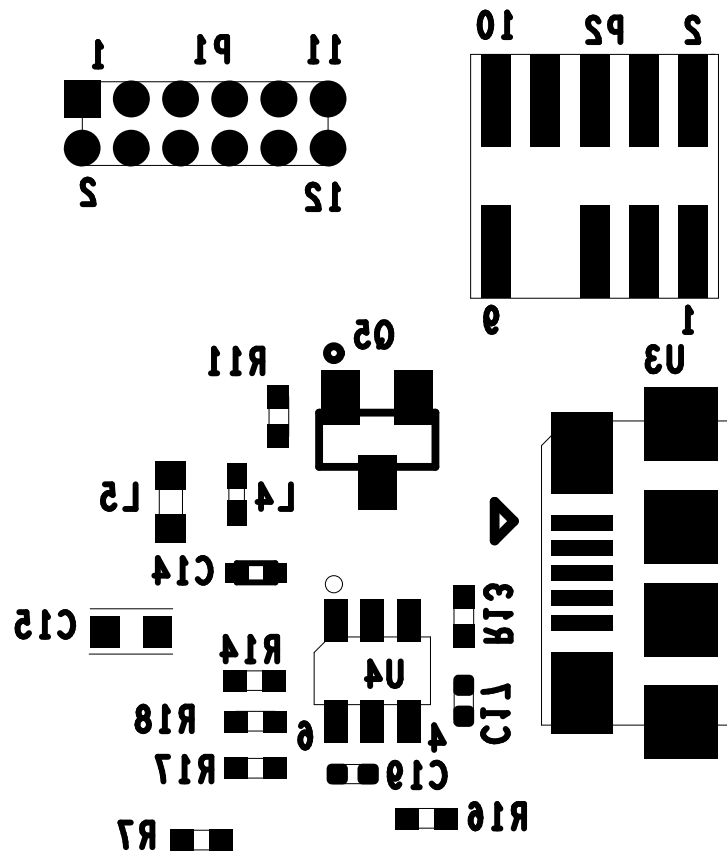
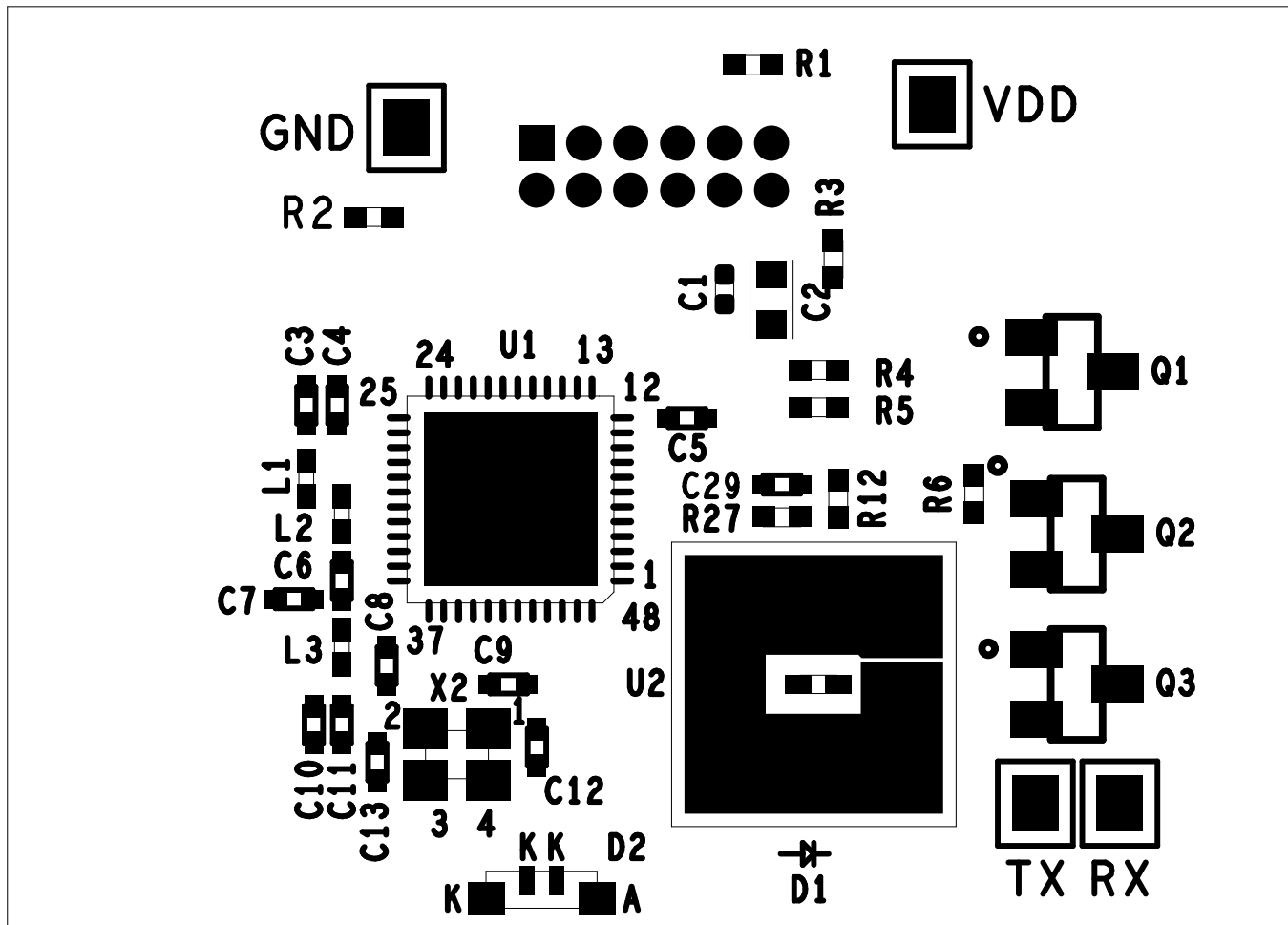


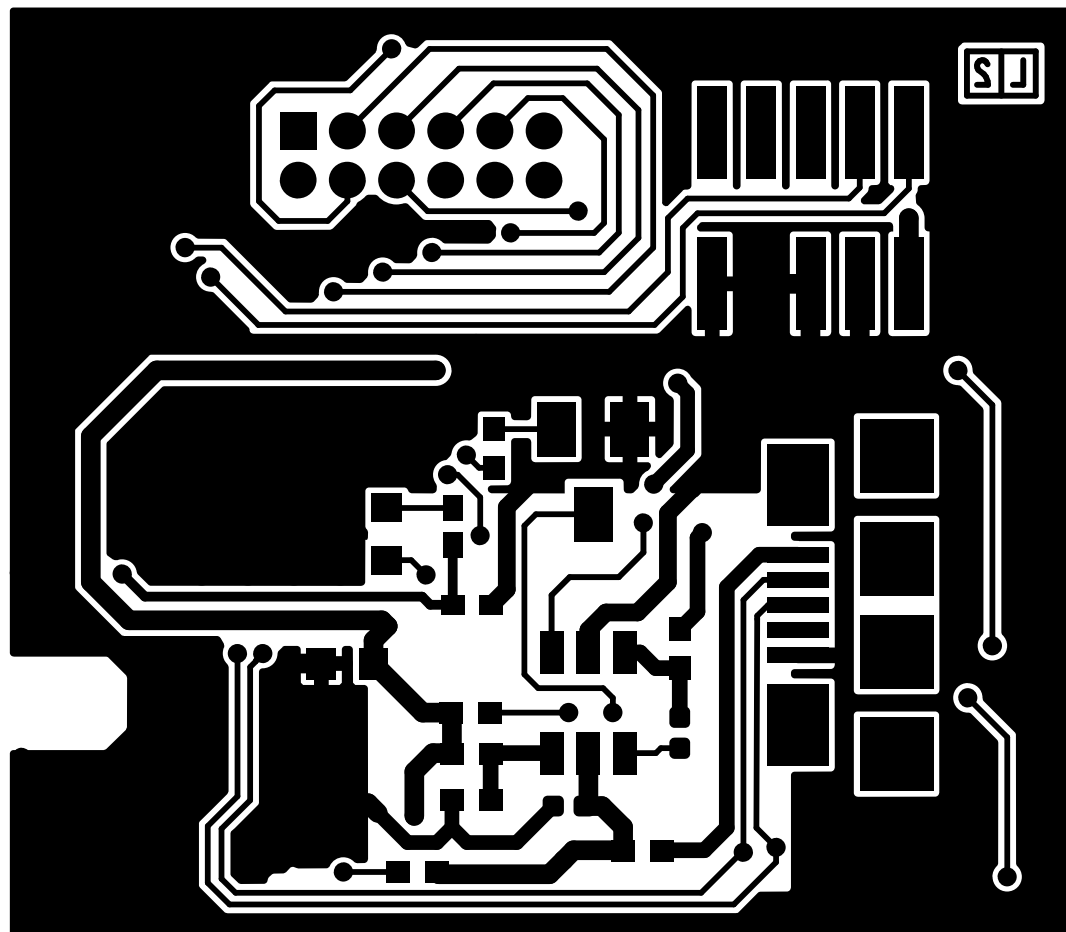
DATE : 19 / 05 / 15
WIRELESS BOARD Rev B
ASSEMBLY BOTTOM



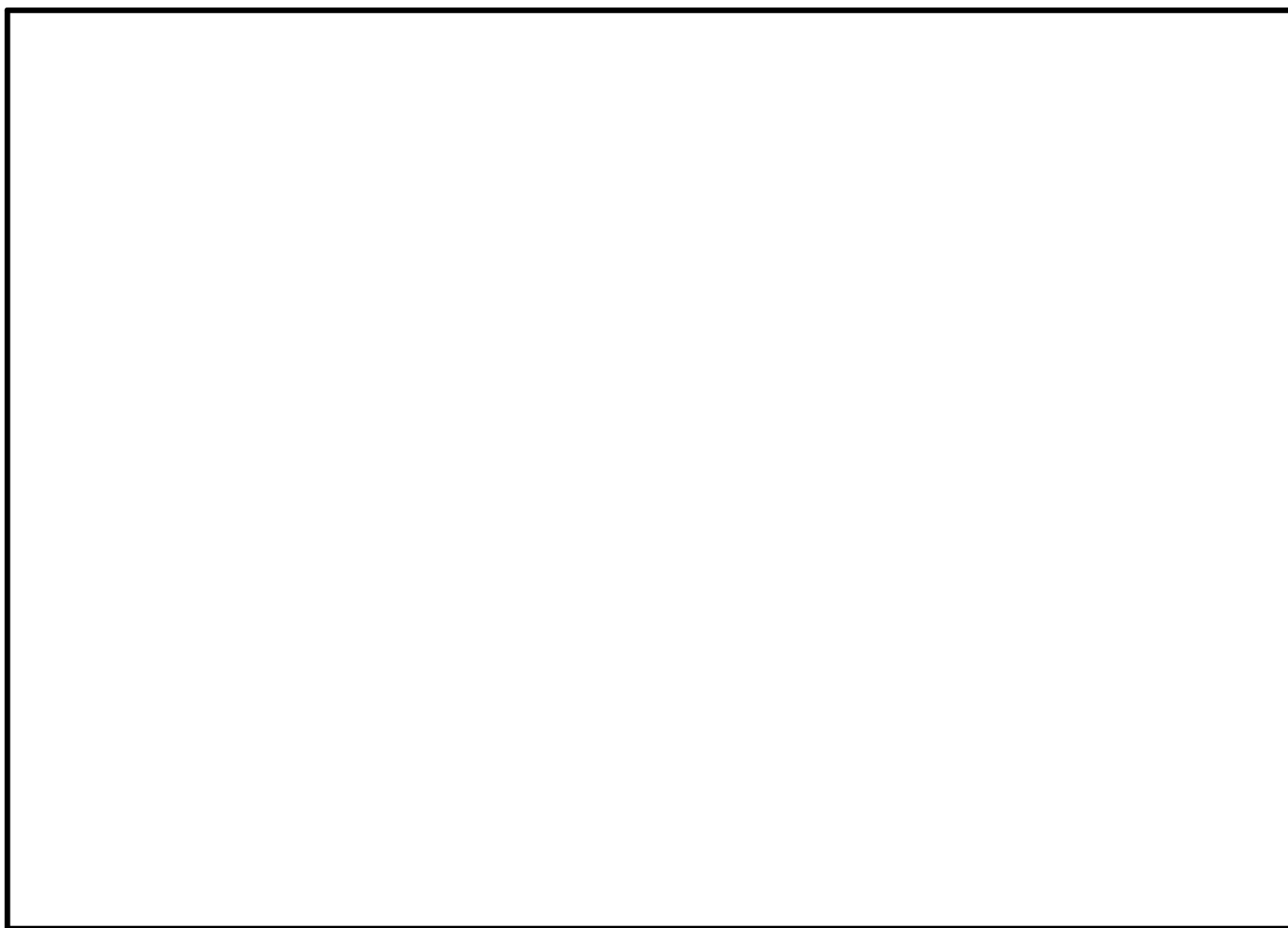
DATE : 19 / 05 / 15
WIRELESS BOARD Rev B
ASSEMBLY TOP



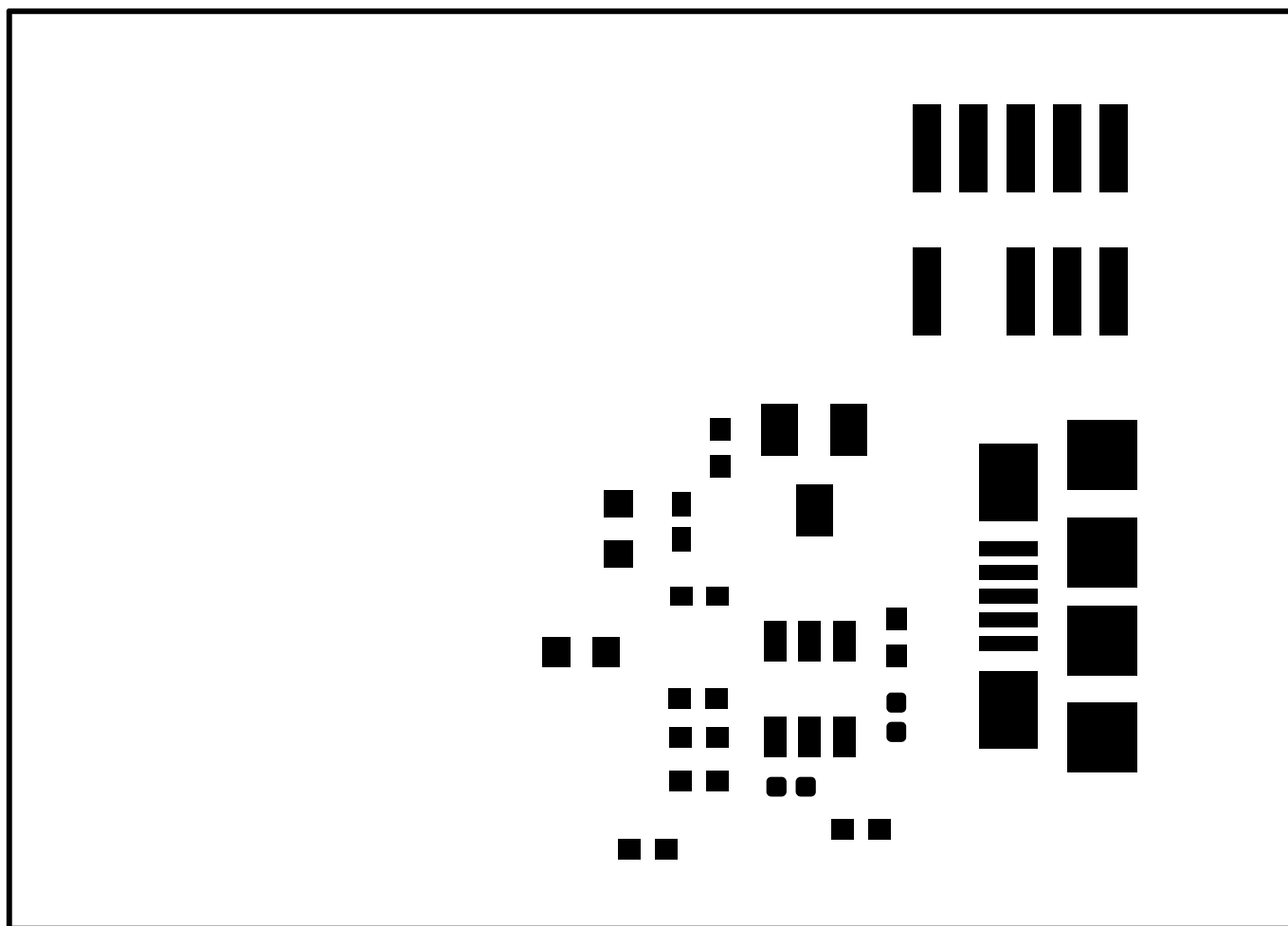
DATE: 19/05/15
WIRELESS_BOARD_Rev_B
BOTTOM



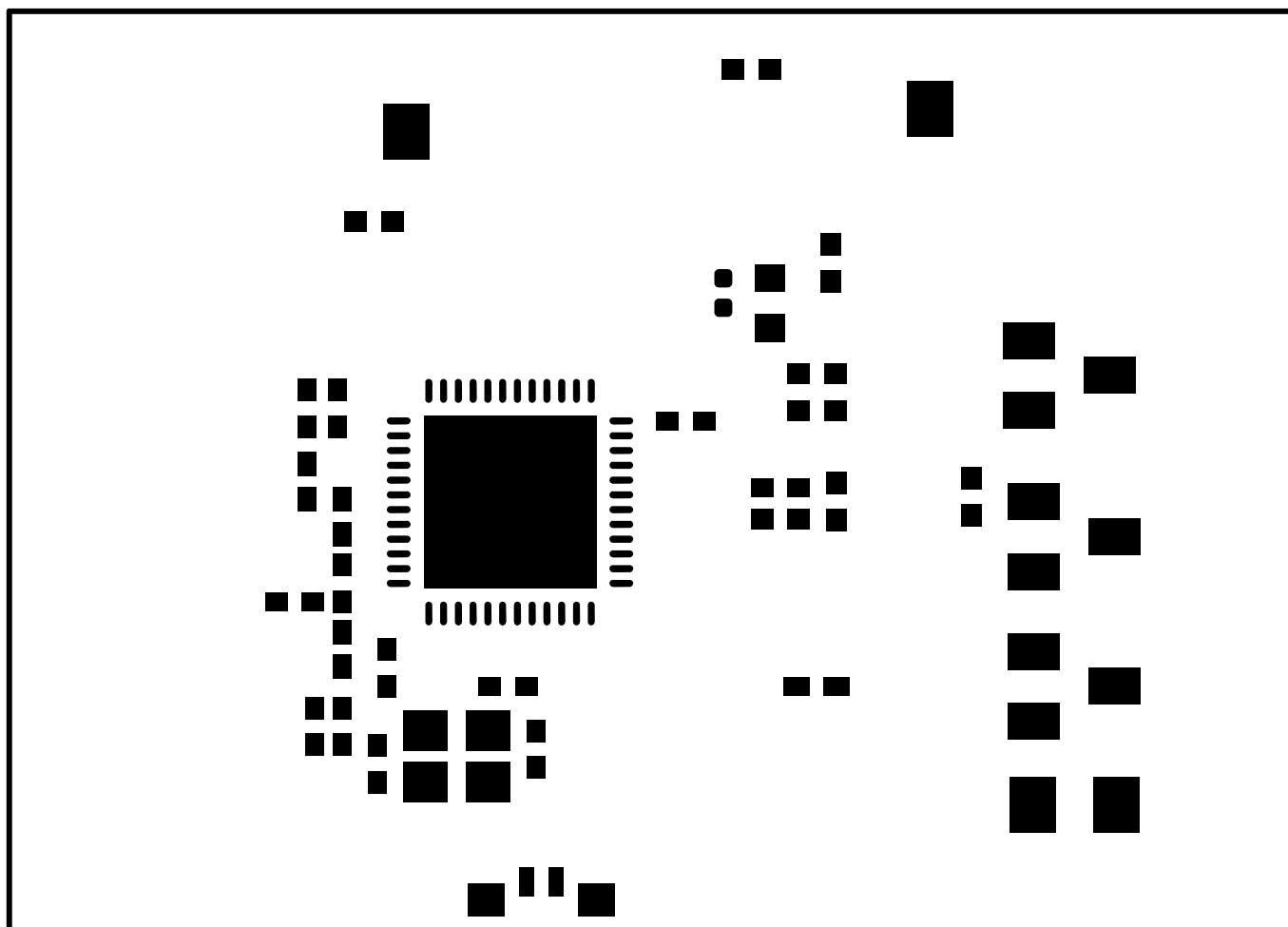
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WIRELESS_BOARD_Rev_B
OUTLINE

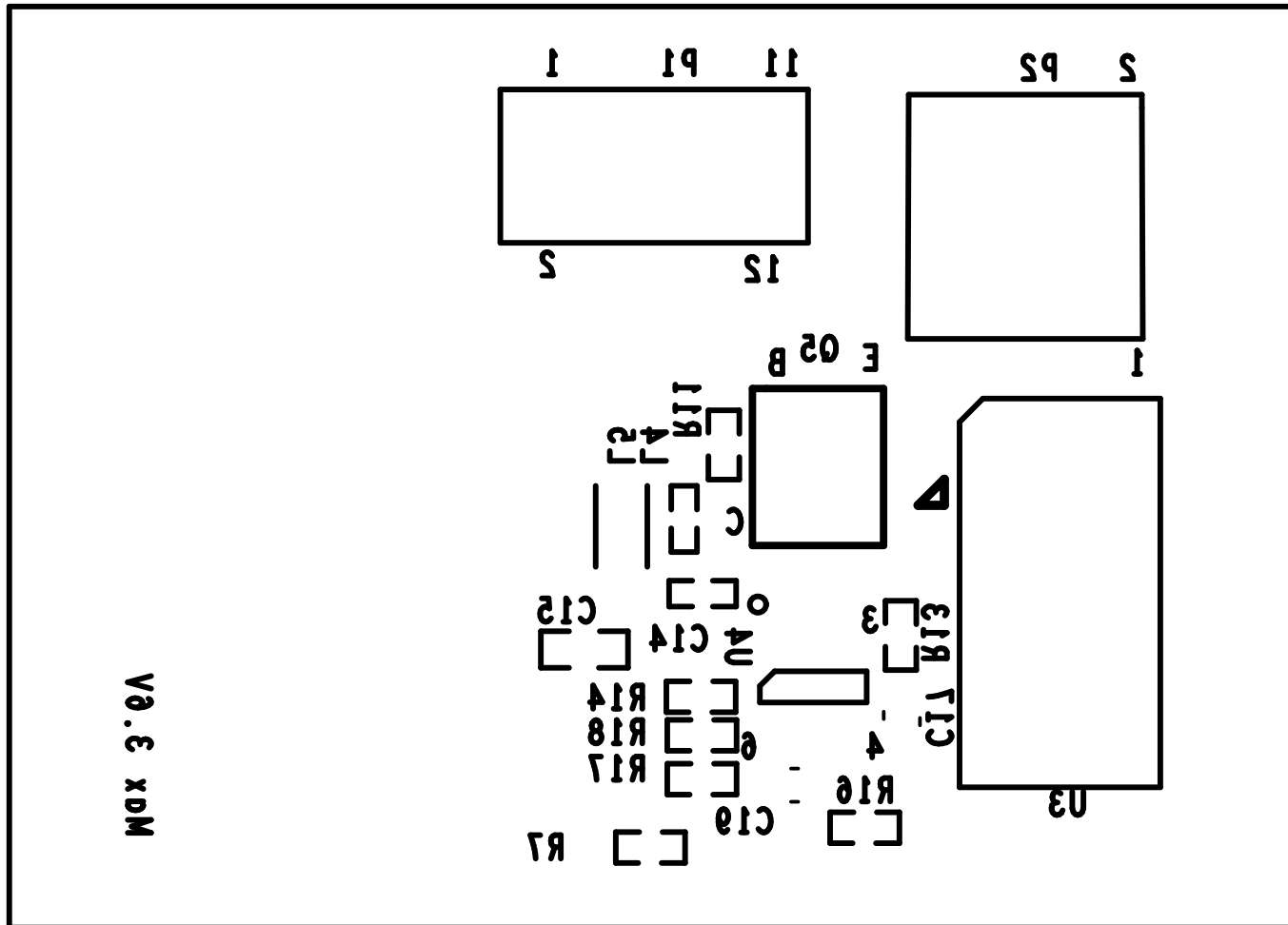


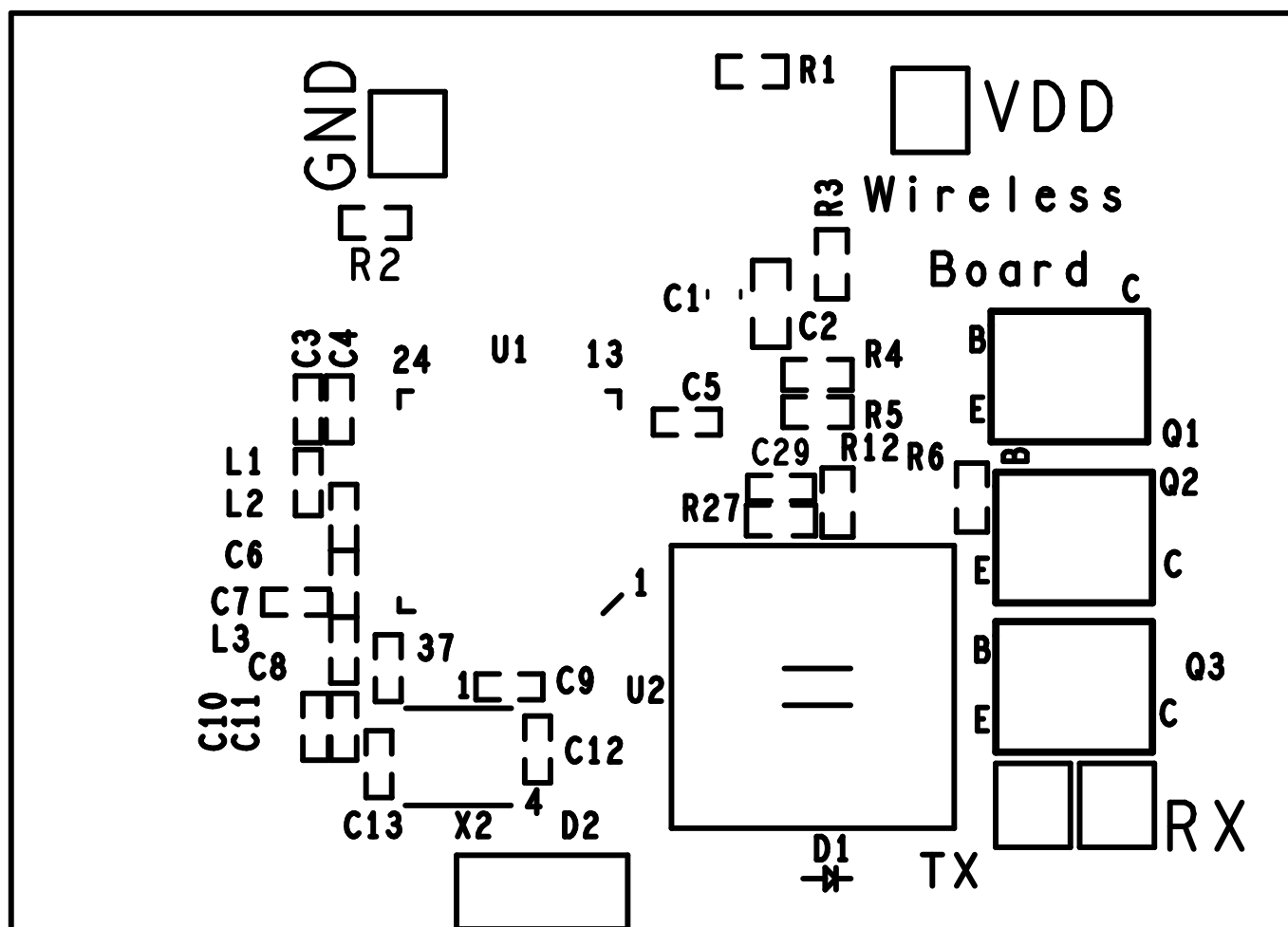
DATE: 19/05/15
WIRELESS_BOARD_Rev_B
PASTE_BOTTOM



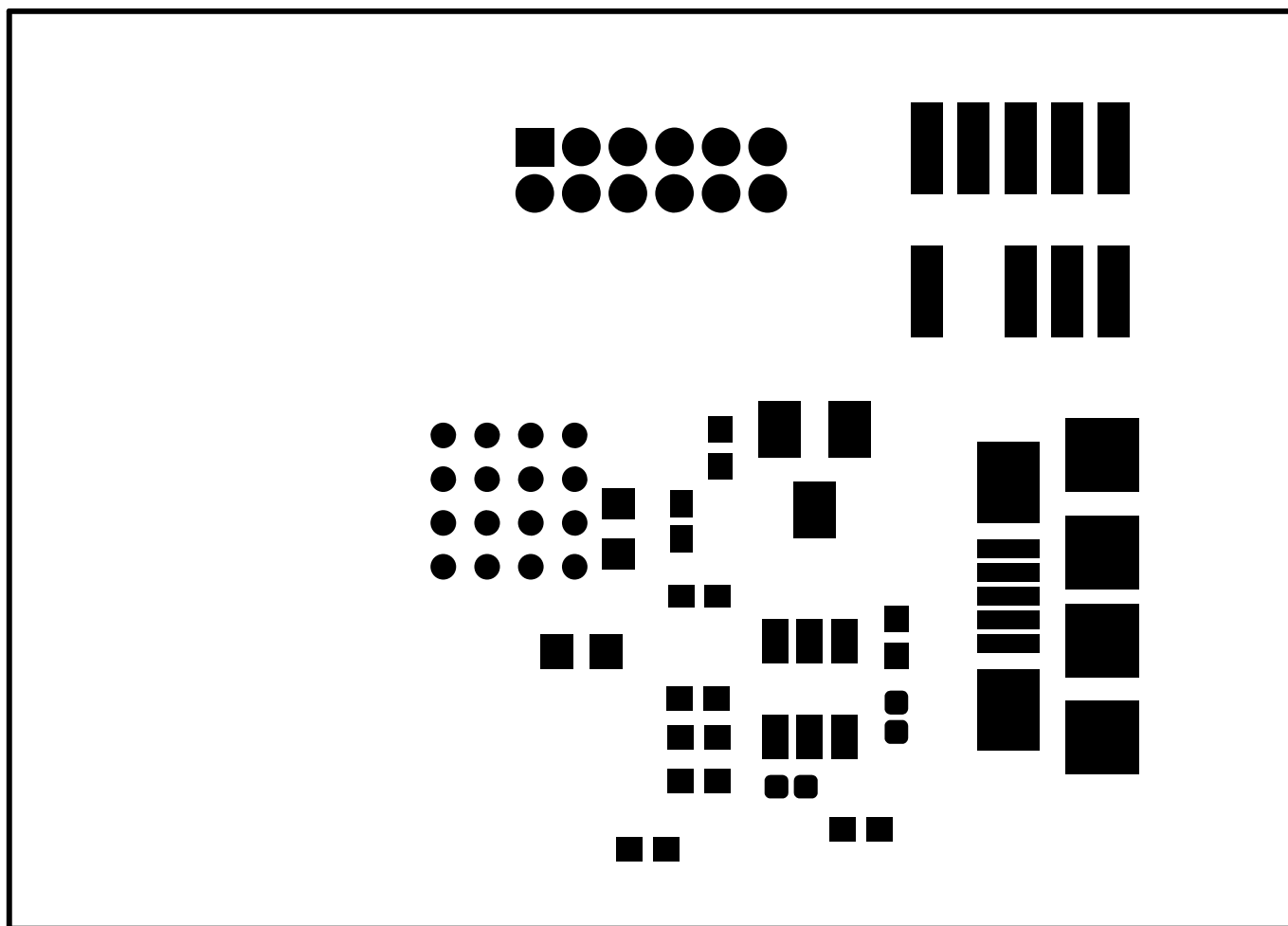
DATE: 19/05/15
WIRELESS_BOARD_Rev_B
PASTE_TOP



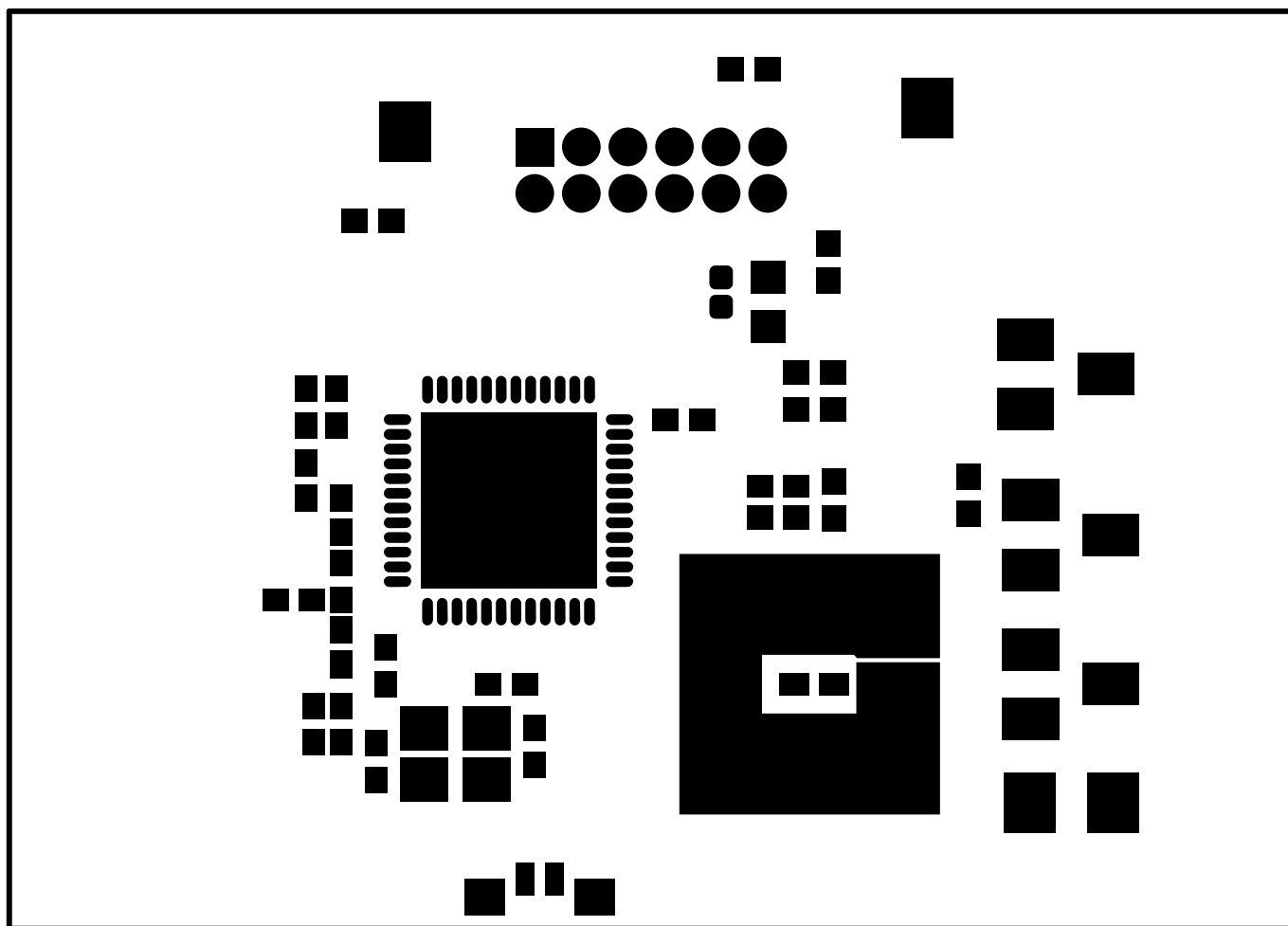




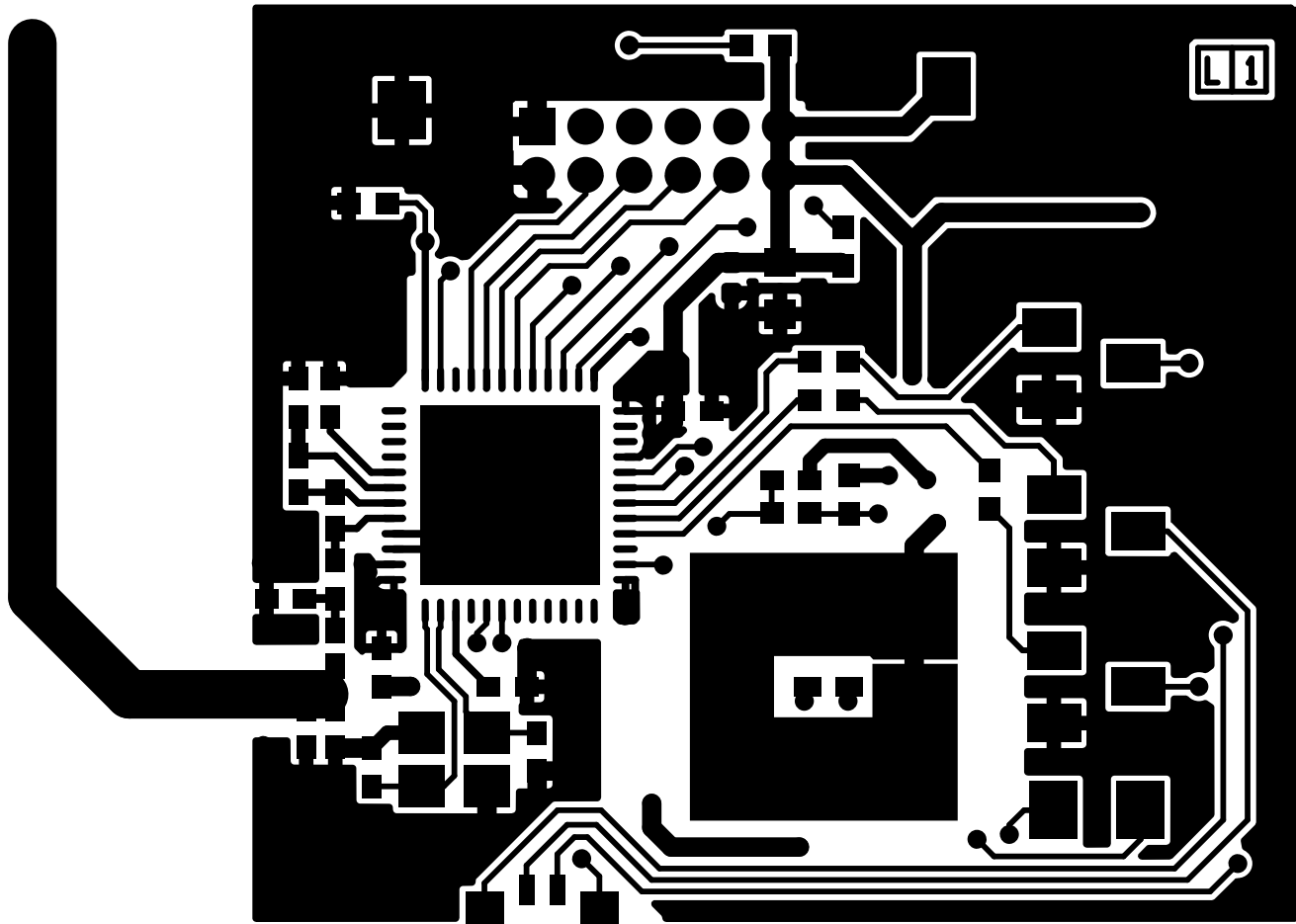
DATE: 19/05/15
WIRELESS_BOARD Rev_B
SOLDMASK_BOTTOM

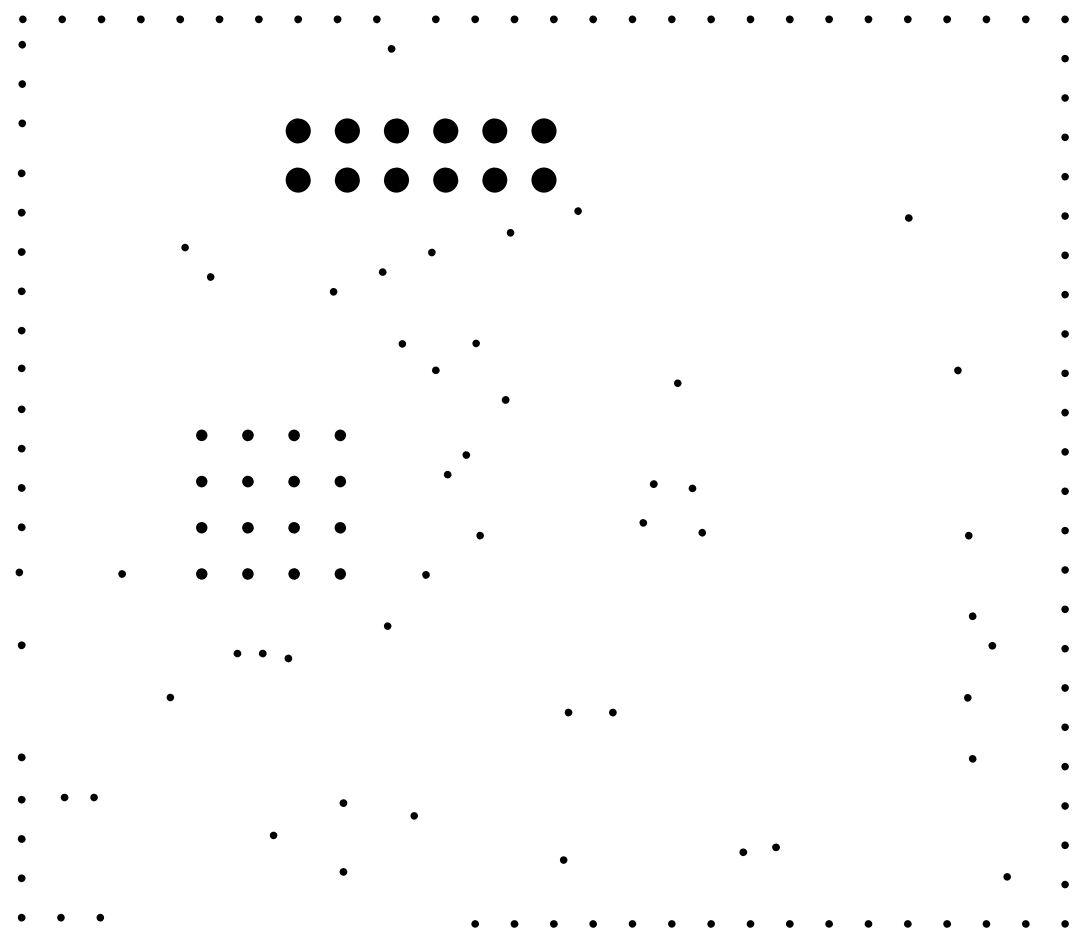


DATE: 19/05/15
WIRELESS_BOARD_Rev_B
SOLDMASK_TOP



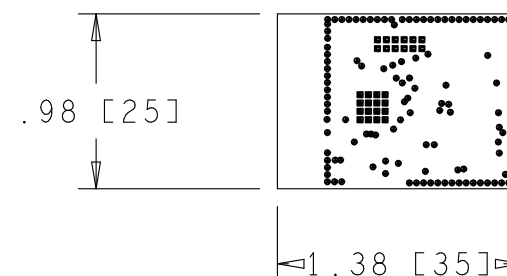
DATE: 19/05/15
WIRELESS_BOARD_Rev_B
TOP





DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	7.9	+3.0/-3.0	PLATED	133
▪	11.8	+3.0/-3.0	PLATED	16
▪	25.6	+3.0/-3.0	PLATED	12

DATE: 19/05/15
WIRELESS_BOARD_Rev_B



NOTES:

1. ALL ARTWORK PATTERNS ARE VIEWED FROM THE TOP.
2. PLATING FINISH METHOD SHALL BE HASL
3. SOLDER MASK OVER BARE COPPER (SMOBC) SHALL BE ON BOTH SIDES.
4. MASK COLOUR IS GREEN AND TYPE IS LPI
5. BOARD THICKNESS IS 1.6 MM
6. COPPER THICKNESS
FOR OUTER LAYERS IS 35 MICRONS
FOR INNER LAYERS IS 35 MICRONS
7. PCB MATERIAL IS FR4
8. STACKUP SPECIFICATIONS IS AS FOLLOWS
9. SIGNAL TRACE WIDTH 6 MILS POWER TRACEWIDTH 30 MILS (MIN 20 MILS)
10. IF VIA IN PAD (VIP) SHOULD BE FILLED AND PLATTED WITH PLANNER

